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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10066643	FILING DATE 02/06/2002	CLASS 257	SUBCLASS 257	GAU 2811	EXAMINER 2816
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\*\*APPLICANTS: Kellar Scot; Kim Sarah; List R.;

\*\*CONTINUING DATA VERIFIED:

\*\* FOREIGN APPLICATIONS VERIFIED:

PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no	219.40605X00
Verified and Acknowledged Examiners's initials	

TITLE : Wafer bonding for three-dimensional (3D) integration

U.S. DEPT. OF COMM./PAT & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
Primary Examiner		Applicati n Examiner	
PREPARED FOR ISSUE			
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